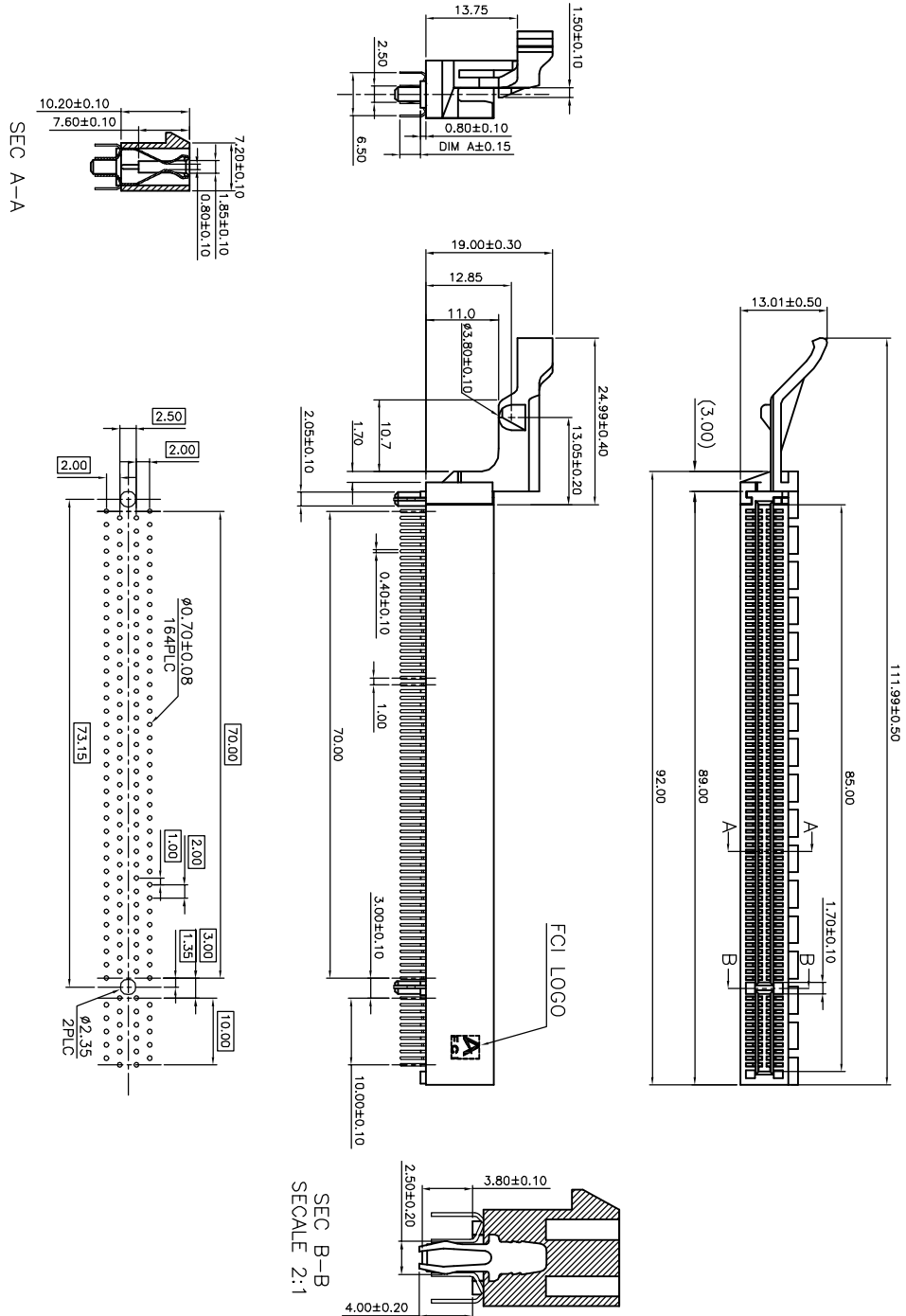
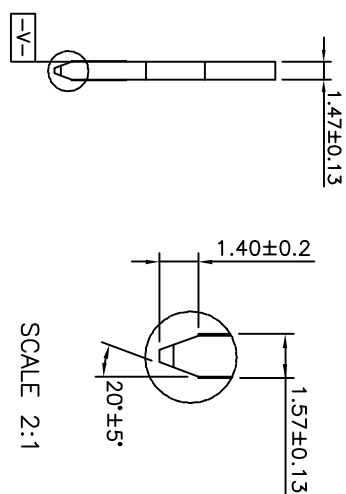
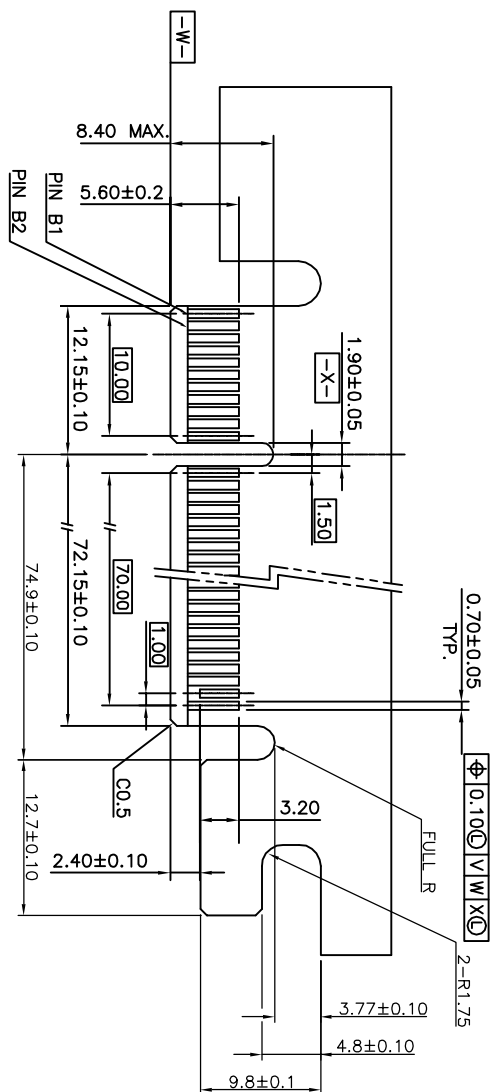


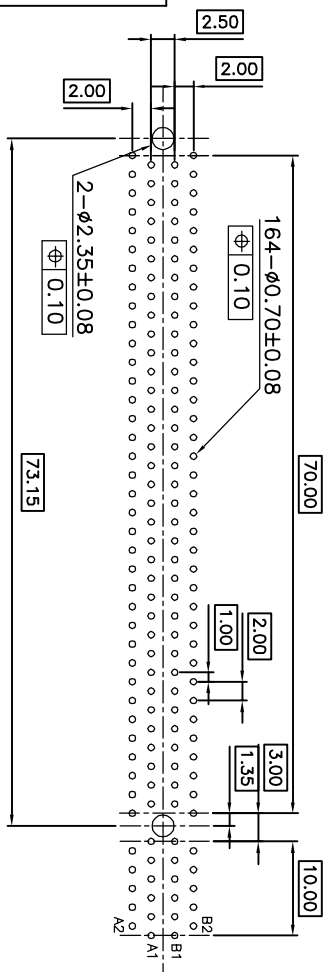
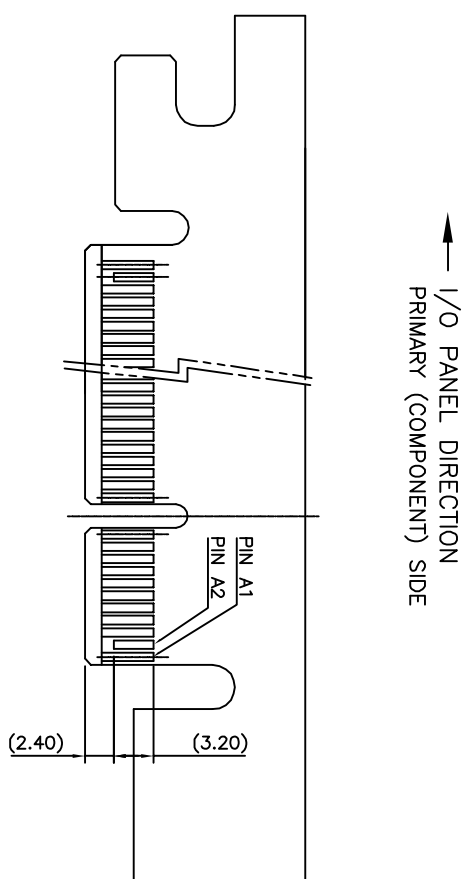


mat'l. code				tolerances unless otherwise specified				CUSTOMER COPY		 www.fci.com			
ltr	ecn no	dr	date	.X ± 0.38		projection		title		product family		EDGE CARD	
A	T05-0046	J,H	2/23/05	.XX ± 0.25				PCI-E INTEGRATED TYPE		size		dwg no	
B	T05-0067	J,H	3/28/05	.XXX ± 0.10				CARD EDGE ASSY		TWN		sheet	
C	T05-0227	J,H	09/30/05	0 ± .2						1 of			
D	T06-0187	J,H	11/13/06	JASON HSU		2/23/05							
E	T07-0125	J,H	08/02/07	engr		JASON HSU		2/23/05					
				chr		STERLING LIN		2/23/05					
				ppd		HC UOU		2/23/05					
sheet	revision	E	E	E									
index	sheet	1	2	3									



SCALE 2:1

ADD-IN CARD EDGE-FINGER DIMENSIONS



RECOMMENDED FOOTPRINT LAYOUT

I/O PANEL DIRECTION →
SECONDARY (SOLDER) SIDE

mat'l. code			tolerances unless otherwise specified			CUSTOMER COPY		 www.fciconnect.com	
itr	ecn no	dr	dtle	linear		 projection	title	PCI-E INTEGRATED TYPE CARD EDGE ASS'Y	code
E				.XX ± 0.25					
				.XXX ± 0.10					
				angles		 MM	product family	EDGE CARD	sheet
				0° ± 2°					
				dr JASON HSU 2/23/05					
				engr JASON HSU 2/23/05		scale	A4	10046742	2 of
				chr STERLING LIN 2/23/05					
				opnd HC LIU 2/23/05					
sheet index	revision sheet								



1 | 2

3

4

NOTES: 1. MATERIAL:

HOUSING: THERMOPLASTIC WITH GLASS FIBER, UL94V-0, COLOR IN BLACK.
LATCHES: THERMOPLASTIC WITH GLASS FIBER, UL94 HB, COLOR IN BLACK.
CONTACTS: COPPER ALLOY.
BOARDLOCKS: COPPER ALLOY.

2. FINISH:

CONTACTS: GOLD PLATING ON CONTACT AREA,
100u"MIN. TIN/LEAD OR 60u" MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDERTAILS,
50u"MIN. NICKEL UNDERPLATING OVER ALL.
BOARDLOCKS: 100u" TIN/LEAD OR MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDERTAILS,
50u"MIN. NICKEL UNDERPLATING OVER ALL.

3. WARNING: THE MAXIMUM ALLOWABLE ANGLE TO WITHDRAWAL THE DAUGHTER CARD FROM RETAINER BY 20 DEGREE.
4. DURABILITY: 50 CYCLES.

5. ROHS COMPATIBLE PRODUCT SPECIFICATIONS

a. PLATING: "LF" MEANS THE PRODUCT IS LEAD FREE, 2.5um min. MATTE PURE TIN OVER 1.27um MIN. NICKEL UNDERPLATE.
b. MANUFACTURING PROCESS COMPATIBILITY: THE HOUSING WILL WITHSTAND EXPOSURE TO 260C±5C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60MM THICK CIRCUIT BOARD.

PRODUCT NUMBER CODE

10046742 -x x x x x x LF

HOUSING COLOR OPTIONS

1-BLACK FOR BASE & RM
2-BLACK FOR BASE & WHITE FOR RM
3-BLUE (287U) FOR BASE & RM
4-BLUE (297U) FOR BASE & RM

PEGS OPTIONS

1-METAL & PLASTIC COMPOUND

TERMINAL PLATING OPTIONS

0-50u" NI UNDERPLATE
30u" Au CONTACT AREA
100u" TIN TAIL AREA
1-50u" NI UNDERPLATE
15u" Au CONTACT AREA
100u" TIN TAIL AREA
2-50u" NI UNDERPLATE
GOLD FLASH CONTACT AREA
100u" TIN TAIL AREA
3-50u" NI UNDERPLATE
30u" Au CONTACT AREA
100u" TIN/LEAD TAIL AREA
4-50u" NI UNDERPLATE
15u" Au CONTACT AREA
100u" TIN/LEAD TAIL AREA
5-50u" NI UNDERPLATE
GOLD FLASH CONTACT AREA
100u" TIN/LEAD TAIL AREA

APPLICATIONS

BLANK - LEAD CONTAIN FOR PLATING OPTIONS 3,4,5
LF - LEAD FREE FOR PLATING OPTIONS 0,1,2

PACKAGING OPTIONS

T-TRAY PACKAGING

POS OPTIONS

3-164

TAIL LENGTH OPTION (DIM A)

1- 3.10MM
2- 2.30MM

mat'l. code		customer		FCI	
lfr	ecn no	dr	date	linear	projection
E				.XX ± 0.25	MM
				.XXX ± 0.10	
				angles	0° ±2°
				dr	JASON HSU 2/23/05
				engr	JASON HSU 2/23/05
				chr	STERLING LIN 2/23/05
				qppd	HC LIU 2/23/05
sheet	revision			scale	1:1
index	sheet				



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PCI-E INTEGRATED TYPE
CARD EDGE ASSY

product family
EDGE CARD

code
TWIN

sheet
3 of

1 | 2

3

4

ACAD

code code
22526